

### DESCRIPTION

The HY514170B is the new generation and fast dynamic RAM organized 262,144 x 16-bit configuration employing advanced submicron CMOS process technology and advanced circuit design technique to achieve fast access time. Independent write of upper and lower byte is controlled by 2 separate WE inputs. Refresh control is provided through RAS-only, CAS-before-RAS, hidden refresh and self refresh modes. The HY514170B conforms to JEDEC pinpoint standards and is available in industry standard 400mil 40pin SOJ and 40/44pin TSOP-II and reverse TSOP-II packages.

### FEATURES

- Low power dissipation
  - Max. battery back-up 1.1mW (L-part)
  - Max. CMOS standby 0.825mW (L-part)
  - 5.5mW

Max. TTL standby 5.5mW  
 Max. Self refresh 1.1mW (SL-part)  
 Max. operating

Speed	Power
60	605.0mW
70	550.0mW
80	495.0mW

- Single power supply of 5V±10%
- TTL compatible inputs and outputs
- Fast access time

Speed	t <sub>TRC</sub>	t <sub>CAC</sub>	t <sub>PC</sub>
60	60ns	15ns	40ns
70	70ns	20ns	40ns
80	80ns	20ns	50ns

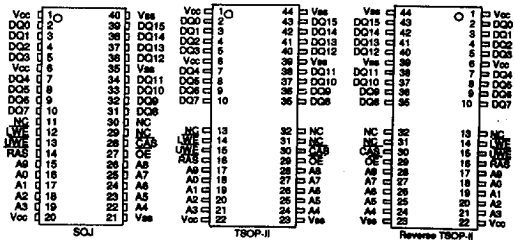
- Fast page mode operation
- 2 WE inputs for upper and lower byte write control
- Read-Modify-Write capability
- CAS-before-RAS, RAS-only, Hidden refresh and Self refresh
- 1024 refresh cycles / 128ms (L-part)
- 1024 refresh cycles / 16ms

### PIN DESCRIPTION

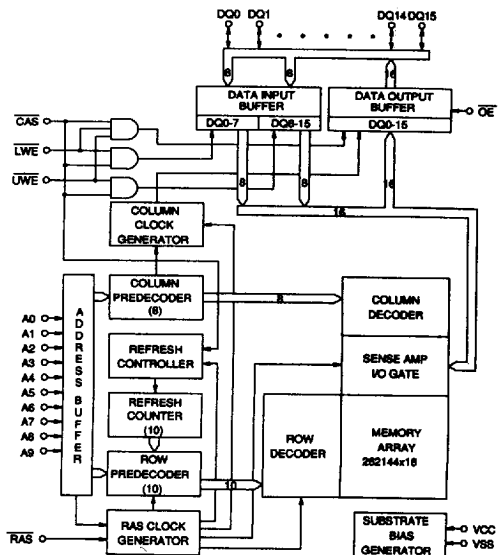
RAS	Row Address Strobe
CAS	Column Address Strobe
LWE, UWE	Write Enable
OE	Output Enable
A0-A9*	Address Input
DQ0-DQ15	Data Input/Output
Vcc	Power (+5V)
VSS	Ground

\* A8 and A9 are applied to row address input only.

### PIN CONNECTION



### BLOCK DIAGRAM



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 1AC21-00-MAY94

**ABSOLUTE MAXIMUM RATINGS**

SYMBOL	PARAMETER	RATING	UNIT
TA	Ambient Temperature	0 to 70	°C
TSTG	Storage Temperature	-55 to 150	°C
VIN, VOUT	Voltage on Any Pin Relative to Vss	-1.0 to 7.0	V
VCC	Voltage on VCC Relative to Vss	-1.0 to 7.0	V
Ios	Short Circuit Output Current	50	mA
Pd	Power Dissipation	1.0	W
TSOLDER	Soldering Temperature* Time	260* 10	°C*sec

NOTE : Operation at or above Absolute Maximum Ratings can adversely affect device reliability.

**RECOMMENDED DC OPERATING CONDITIONS**

(TA= 0°C to 70°C)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
VCC	Supply Voltage	4.5	5.0	5.5	V
VIH	Input High Voltage	2.4	-	VCC+ 1.0	V
VIL	Input Low Voltage	-1.0	-	0.8	V

NOTE : All voltages are referenced to Vss.

**DC CHARACTERISTICS**

(TA= 0°C to 70°C, VCC= 5V± 10%, VSS= 0V, unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS	SPEED/ POWER	MIN.	MAX.	UNIT	NOTE
I <sub>LI</sub>	Input Leakage Current (Any Input Pins)	VSS ≤ V <sub>IN</sub> ≤ 6.5V, All other pins not under test= VSS		-10	10	μA	
I <sub>LO</sub>	Output Leakage Current (High Impedance State)	VSS ≤ V <sub>OUT</sub> ≤ 5.5V, RAS & CAS at V <sub>IH</sub>		-10	10	μA	
I <sub>CC1</sub>	Vcc Supply Current, Operating	t <sub>RC</sub> = t <sub>RC</sub> (min.)	60 70 80	- - -	110 100 90	mA	1,2,3
I <sub>CC2</sub>	Vcc Supply Current, TTL Standby	RAS & CAS at V <sub>IH</sub> , other inputs ≥ VSS		-	1	mA	
I <sub>CC3</sub>	Vcc Supply Current, RAS-only refresh	t <sub>RC</sub> = t <sub>RC</sub> (min.)	60 70 80	- - -	110 100 90	mA	1,2,3
I <sub>CC4</sub>	Vcc Supply Current, Fast Page mode	t <sub>PC</sub> = t <sub>PC</sub> (min.)	60 70 80	- - -	60 50 45	mA	1,2,3
I <sub>CC5</sub>	Vcc Supply Current, CMOS Standby	RAS & CAS ≥ VCC-0.2V	L-part	-	1 0.15	mA	5
I <sub>CC6</sub>	Vcc Supply Current, CAS-before-RAS refresh	t <sub>RC</sub> = t <sub>RC</sub> (min.)	60 70 80	- - -	110 100 90	mA	1,2,3
I <sub>CC7</sub>	Vcc Supply Current, Battery Back Up (L-part only)	t <sub>RC</sub> = 125μs, t <sub>RAS</sub> ≤ 1μs CAS= CBR cycling or 0.2V OE & WE= VCC-0.2V, A0-A9= VCC-0.2V or 0.2V DQ0-DQ15= 0.2V, VCC-0.2V or open		-	200	μA	1,4,5
I <sub>CC8</sub>	Vcc Supply Current, Self refresh (SL-part only)	RAS & CAS ≤ 0.2V other pins same as I <sub>CC7</sub>		-	200	μA	5
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 4.2mA		-	0.4	V	
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -5mA		2.4	-	V	

**NOTE :**

- I<sub>CC1</sub>, I<sub>CC3</sub>, I<sub>CC4</sub>, I<sub>CC6</sub> and I<sub>CC7</sub> depend on cycle rate.
- I<sub>CC1</sub>, I<sub>CC3</sub>, I<sub>CC4</sub> and I<sub>CC6</sub> are dependent on output loading. Specified values are obtained with the output open.
- I<sub>CC</sub> is specified as average current. I<sub>CC1</sub>, I<sub>CC3</sub>, I<sub>CC6</sub>, Address can be changed maximum two times while RAS= V<sub>IL</sub>. I<sub>CC4</sub>, Address can be changed maximum once while CAS= V<sub>IH</sub>.
- Only t<sub>RAS</sub>(max.)= 1μs is applied to refresh of battery backup but t<sub>RAS</sub>(max.)= 10μs is applied to normal functional operation.
- I<sub>CC5</sub>(max.)= 0.15mA and I<sub>CC7</sub> are applied to L-parts (HY514170BLJC, HY514170BLTC and HY514170BLRC, HY514170BSLJC, HY514170BSLTC and HY514170BSLRC).
- I<sub>CC8</sub> is applied to SL-parts only (HY514170BSLJC, HY514170BSLTC and HY514170BSLRC).

**AC CHARACTERISTICS**

(TA= 0°C to 70°C, VCC= 5V± 10%, VSS= 0V, unless otherwise noted.) NOTE : 1, 2, 3, 13

#	SYMBOL	PARAMETER	HY514170BJC/TC/RC/LJC/LTC/LRC/ SLJC/SLTC/SLRC						UNIT	NOTE
			-60		-70		-80			
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
1	tRC	Random Read or Write Cycle Time	110	-	130	-	150	-	ns	
2	tRWC	Read-Modify-Write Cycle Time	155	-	170	-	200	-	ns	
3	tPC	Fast Page Mode Cycle Time	40	-	40	-	50	-	ns	
4	tPRWC	Fast Page Mode Read-Modify-Write Cycle Time	80	-	80	-	100	-	ns	
5	tRAC	Access Time from RAS	-	60	-	70	-	80	ns	4,9,10
6	tCAC	Access Time from CAS	-	15	-	20	-	20	ns	4,9
7	tAA	Access Time from Column Address	-	30	-	35	-	40	ns	4,10
8	tCPA	Access Time from Column Precharge	-	35	-	35	-	45	ns	4
9	tCLZ	CAS to Output Low Impedance	0	-	0	-	0	-	ns	4
10	tOFF	Output Buffer Turn-off Delay	0	15	0	15	0	15	ns	5
11	tT	Transition Time (Rise and Fall)	3	50	3	50	3	50	ns	3
12	tRP	RAS Precharge Time	40	-	50	-	60	-	ns	
13	tRAS	RAS Pulse Width	60	10K	70	10K	80	10K	ns	
14	tRASP	RAS Pulse Width (Fast Page Mode)	60	100K	70	100K	80	100K	ns	
15	tRSH	RAS Hold Time	15	-	20	-	20	-	ns	
16	tCSH	CAS Hold Time	60	-	70	-	80	-	ns	
17	tCAS	CAS Pulse Width	15	10K	20	10K	20	10K	ns	
18	tRCD	RAS to CAS Delay	15	45	20	50	20	60	ns	9
19	tRAD	RAS to Column Address Delay Time	15	30	15	35	15	40	ns	10
20	tCRP	CAS to RAS Precharge Time	5	-	5	-	5	-	ns	
21	tCP	CAS Precharge Time	10	-	10	-	10	-	ns	
22	tASR	Row Address Set-up Time	0	-	0	-	0	-	ns	
23	tRAH	Row Address Hold Time	10	-	10	-	10	-	ns	
24	tASC	Column Address Set-up Time	0	-	0	-	0	-	ns	
25	tCAH	Column Address Hold Time	15	-	15	-	15	-	ns	
26	tAR	Column Address Hold Time from RAS	50	-	55	-	60	-	ns	
27	tRAL	Column Address to RAS Lead Time	30	-	35	-	40	-	ns	
28	tRCS	Read Command Set-up Time	0	-	0	-	0	-	ns	17
29	tRCH	Read Command Hold Time Referenced to CAS	0	-	0	-	0	-	ns	6,14
30	tRRH	Read Command Hold Time Referenced to RAS	0	-	0	-	0	-	ns	6,14
31	tWCH	Write Command Hold Time	15	-	15	-	15	-	ns	16
32	tWCR	Write Command Hold Time from RAS	50	-	55	-	60	-	ns	16
33	tWP	Write Command Pulse Width	10	-	10	-	10	-	ns	15,16
34	tRWL	Write Command to RAS Lead Time	20	-	20	-	20	-	ns	15
35	tCWL	Write Command to CAS Lead Time	20	-	20	-	20	-	ns	15,18
36	tDS	Data-In Set-up Time	0	-	0	-	0	-	ns	7,14
37	tDH	Data-In Hold Time	15	-	15	-	15	-	ns	7,15
38	tDHR	Data-In Hold Time Referenced to RAS	50	-	55	-	60	-	ns	
39	tREF	Refresh Period (1024 cycles)		16		16		16	ms	12
		L-part		128		128		128	ms	11
40	tWCS	Write Command Set-up Time	0	-	0	-	0	-	ns	8,15

**NOTE :**

1. An initial pause of 200 $\mu$ s is required after power-up followed by 8 RAS cycles before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8 CAS-before-RAS initialization cycles instead of 8 RAS-only refresh cycles are required.
2. If RAS= Vss during power-up, the HY514170B could begin active cycle. This condition results in higher current than necessary current which is demanded from the power supply during power-up. It is recommended that RAS and CAS track with Vcc during power-up or be held at a valid VIH in order to minimize the power-up current.
3. VIH(min.) and VIL(max.) are reference levels for measuring timing of input signals. Also, transition times are measured between VIH(min.) and VIL(max.), and are assumed to be 5ns for all inputs.
4. Measured at VOH= 2.4V and VOL= 0.4V with a load equivalent to 2 TTL loads and 100pF.
5. toFF(max.) and toEZ define the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
6. Either trCH or trRH must be satisfied for a read cycle.
7. These parameters are referenced to CAS leading edge in early write cycles and to LWE or UWE leading edge in Read-Modify-Write cycles.
8. twCS, trWD, tcWD, tAWD and tCPWD are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If twCS $\geq$  twCS(min.), the cycle is an early write cycle and data out pin will remain open circuit (high impedance) through the entire cycle. If trWD $\geq$  trWD(min.), tcWD $\geq$  tcWD(min.), tAWD $\geq$  tAWD(min.), and tCPWD $\geq$  tCPWD(min.), the cycle is a Read-Modify-Write cycle and data out will contain data read from the selected cell. If neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indetermined.
9. Operation within the trCD(max.) limit insures that trAC(max.) can be met. trCD(max.) is specified as a reference point only. If trCD is greater than the specified trCD(max.) limit, then access time is controlled by tcAC.
10. Operation within the trAD(max.) limit insures that trAC(max.) can be met. trAD(max.) is specified as a reference point only. If trAD is greater than the specified trAD(max.) limit, then access time is controlled by tAA.
11. tREF(max.)= 128ms is applied to L-parts (HY514170BLJC, HY514170BLTC, HY514170BLRC, HY514170BSLJC, HY514170BSLTC and HY514170BSLRC).
12. A burst of 1024 CAS-before-RAS refresh cycles must be executed within 16ms (128ms for L-part) after exiting self refresh.
13. When both LWE and UWE go low at the same time, all 16-bits data are written into the device. LWE and UWE must be transitioned simultaneously within a same read or write cycle.
14. These parameters are determined by the earlier falling edge of LWE or UWE.
15. These parameters are determined by the later falling edge of LWE or UWE.
16. These parameters are determined by the earlier rising edge of LWE or UWE.
17. These parameters are determined by the later rising edge of LWE or UWE.
18. tcWL must be satisfied by both LWE and UWE for 16-bits access cycles.

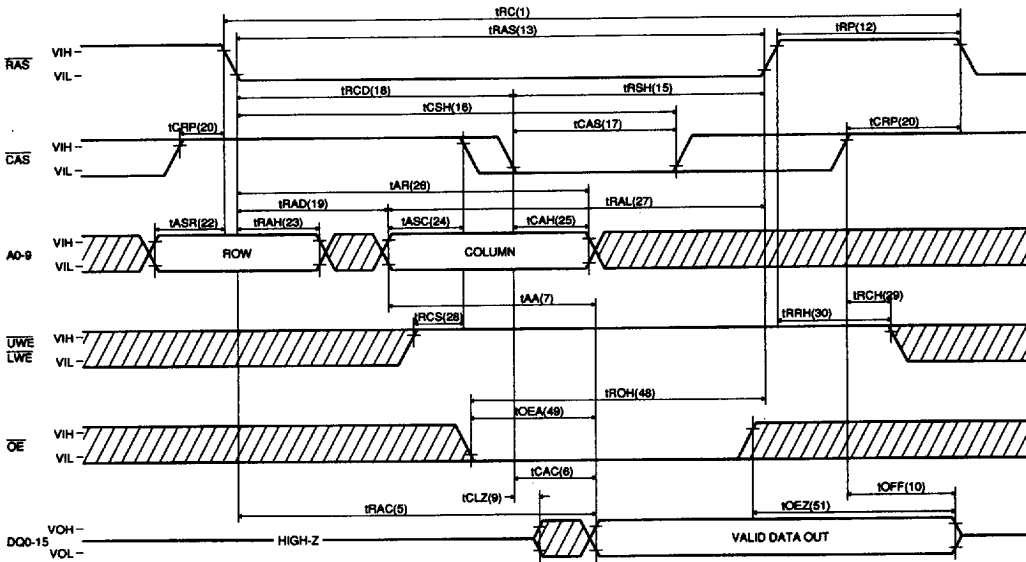
**CAPACITANCE**

(TA= 25°C, VCC= 5V $\pm$  10%, VSS= 0V, f= 1MHz, unless otherwise noted.)

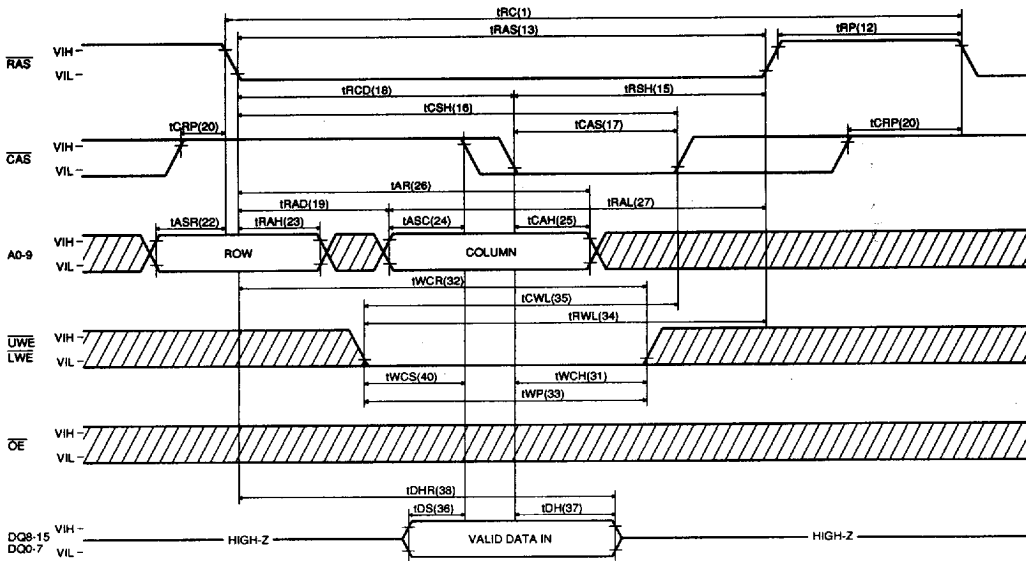
SYMBOL	PARAMETER	TYP.	MAX.	UNIT
CIN1	Input Capacitance (A0-A9)	-	5	pF
CIN2	Input Capacitance (RAS, CAS, LWE, UWE, OE)	-	7	pF
CDQ	Data Input/Output Capacitance (DQ0-DQ15)	-	7	pF

**TIMING DIAGRAM**

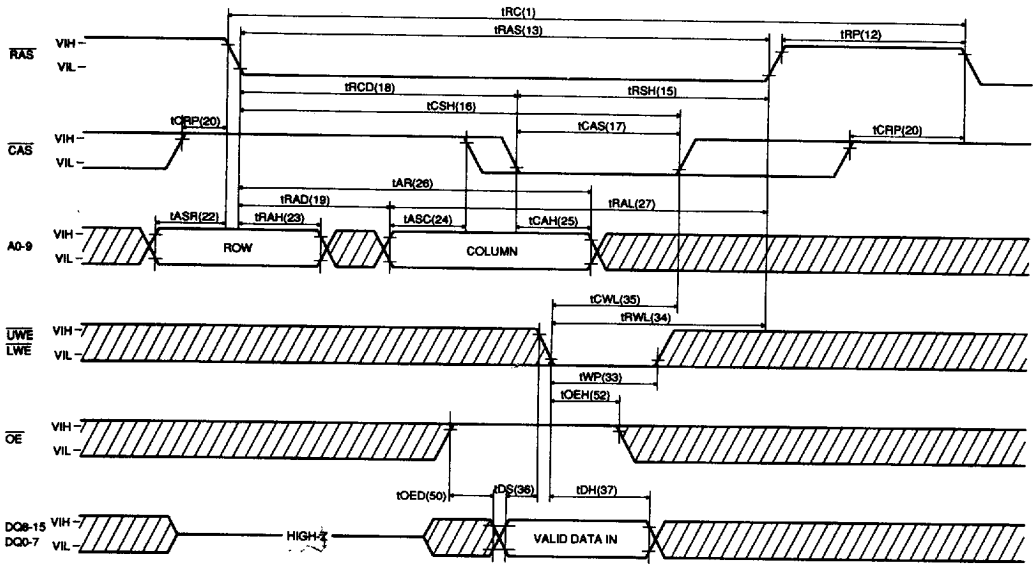
**READ CYCLE**



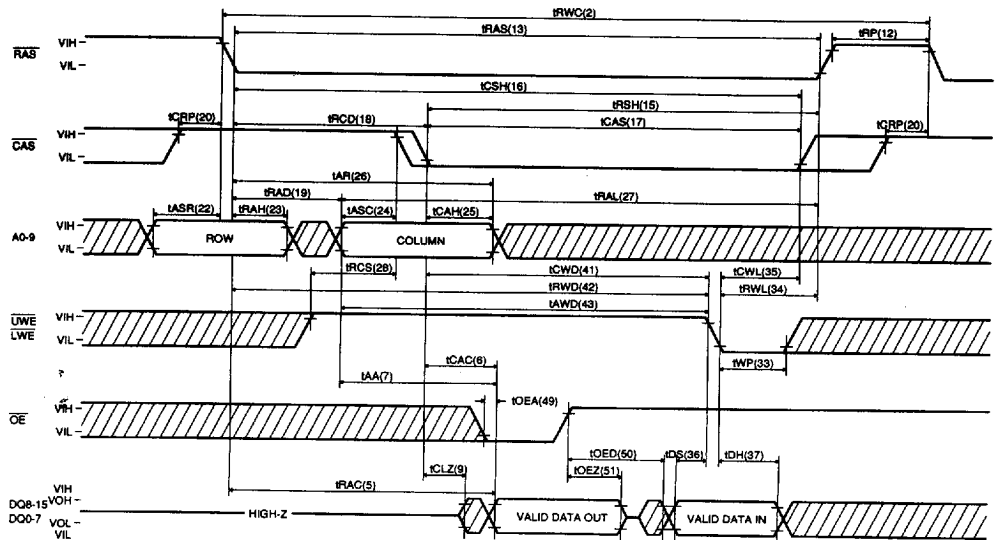
**EARLY WRITE CYCLE**



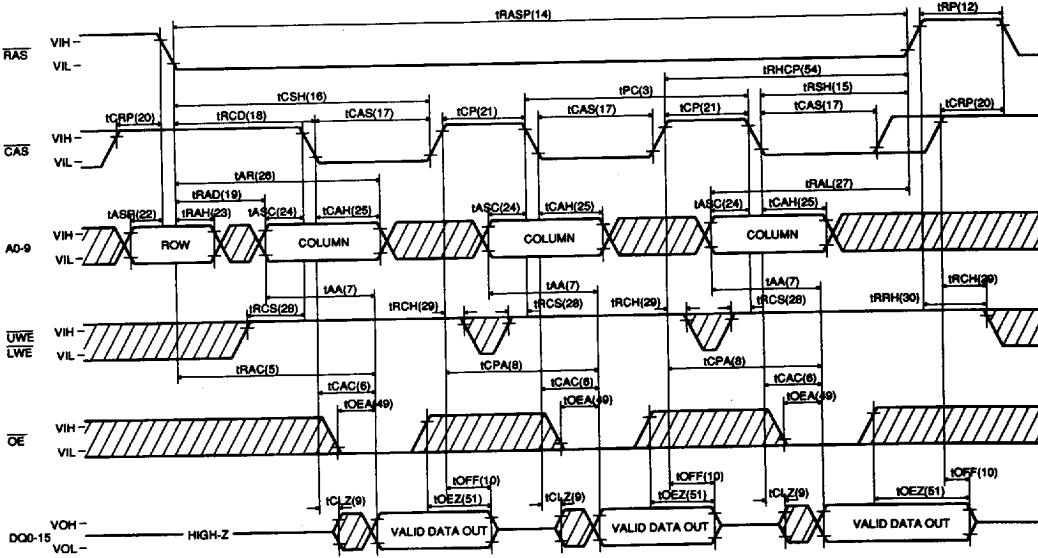
**WRITE CYCLE ( $\overline{OE}$  CONTROLLED WRITE)**



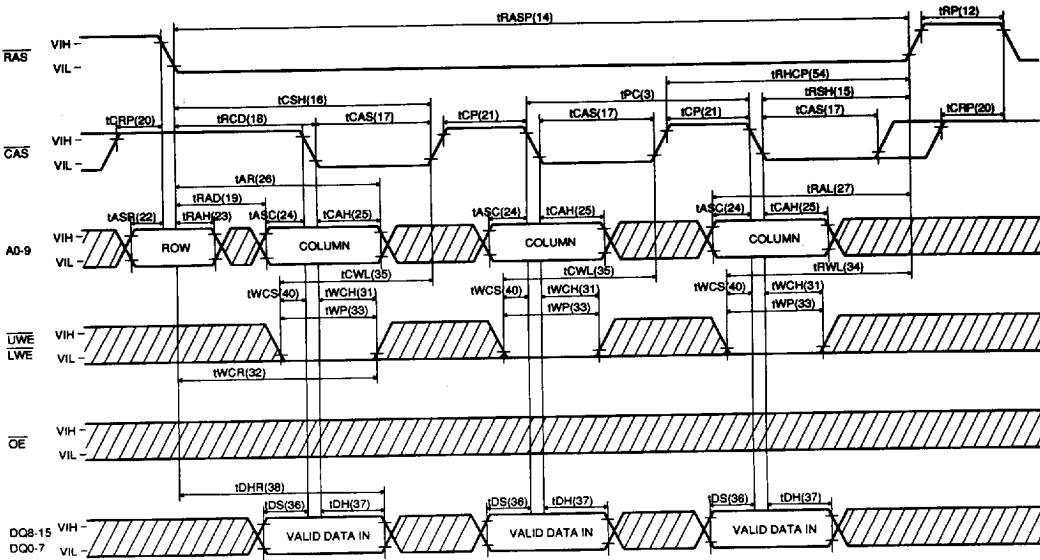
**READ-MODIFY-WRITE CYCLE**



FAST PAGE MODE READ CYCLE



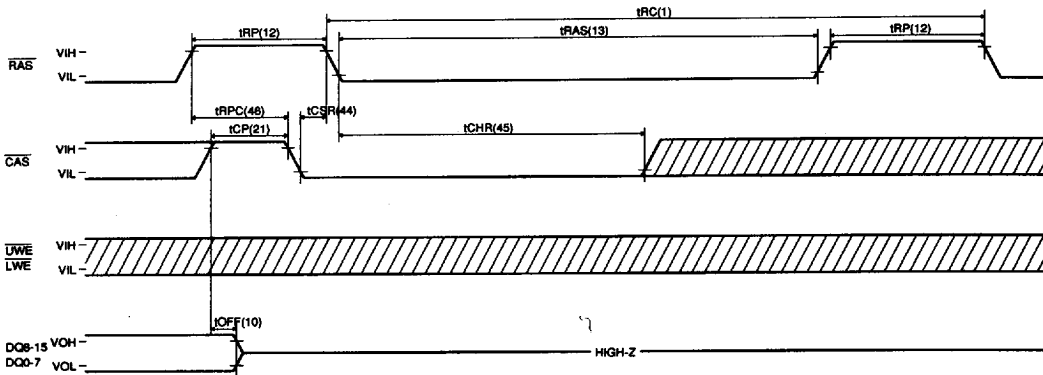
FAST PAGE MODE EARLY WRITE CYCLE





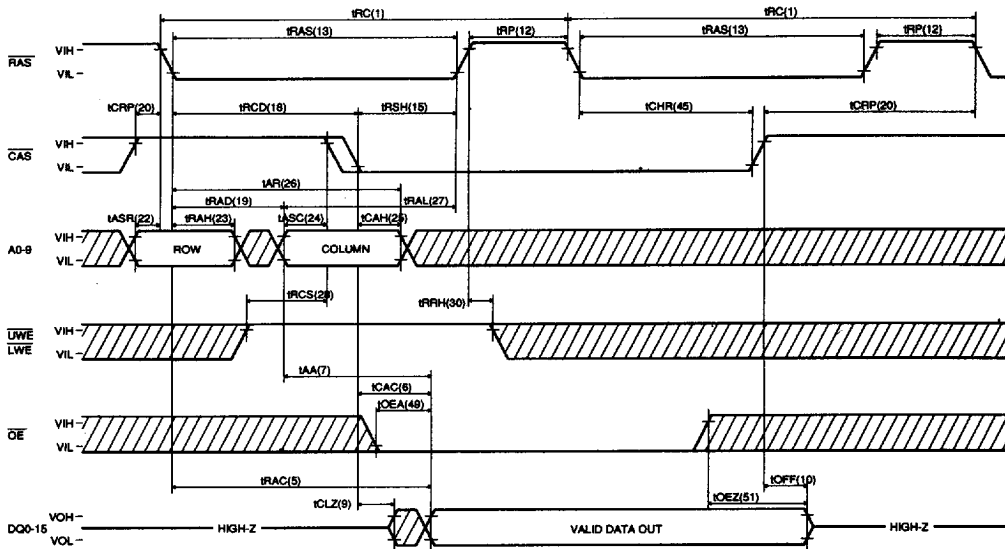


**CAS-BEFORE-RAS REFRESH CYCLE**

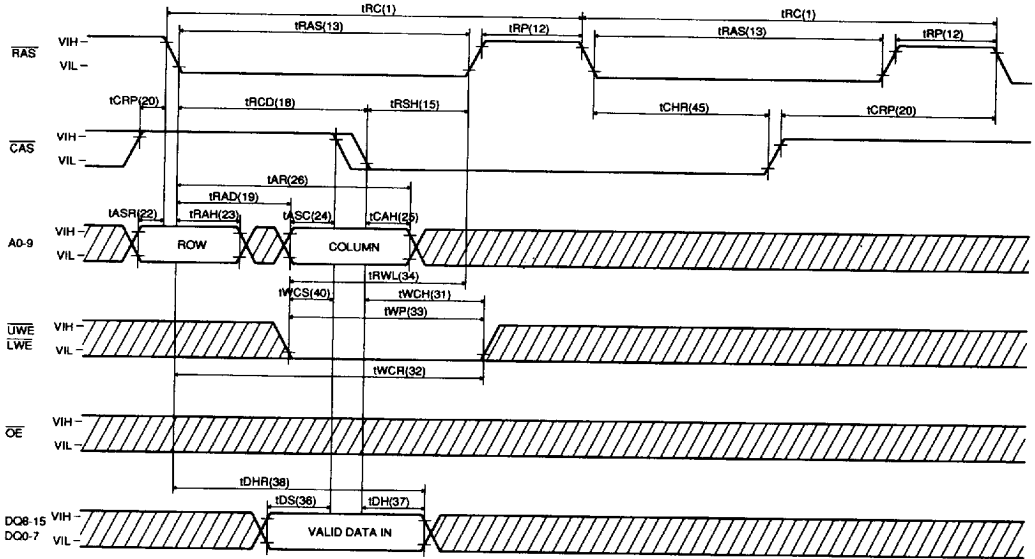


NOTE : A0-9 and OE = "H" or "L"

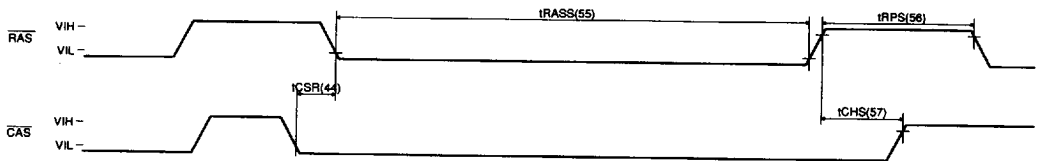
**HIDDEN REFRESH CYCLE (READ)**



**HIDDEN REFRESH CYCLE (WRITE)**

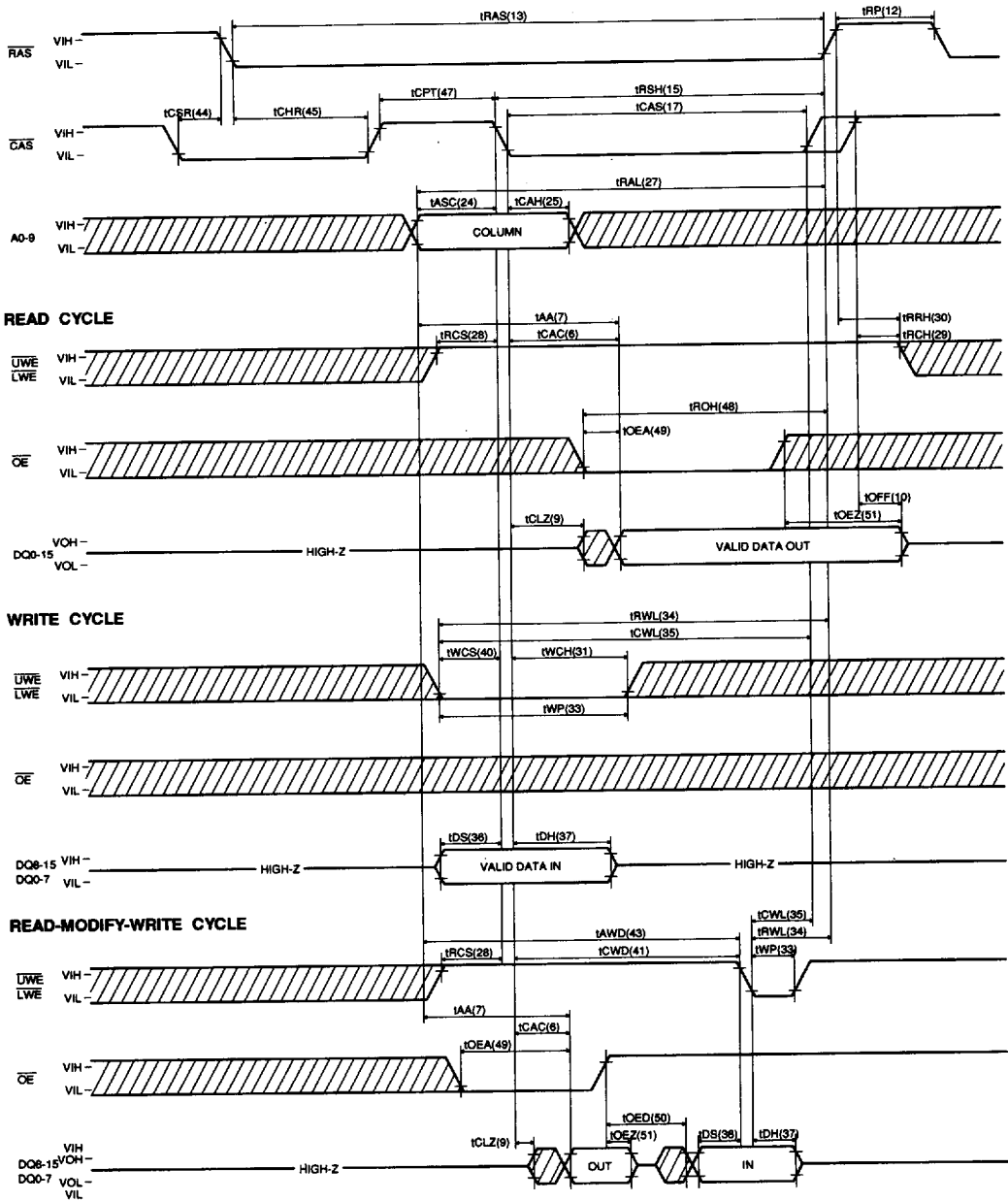


**CAS-BEFORE-RAS SELF REFRESH CYCLE**



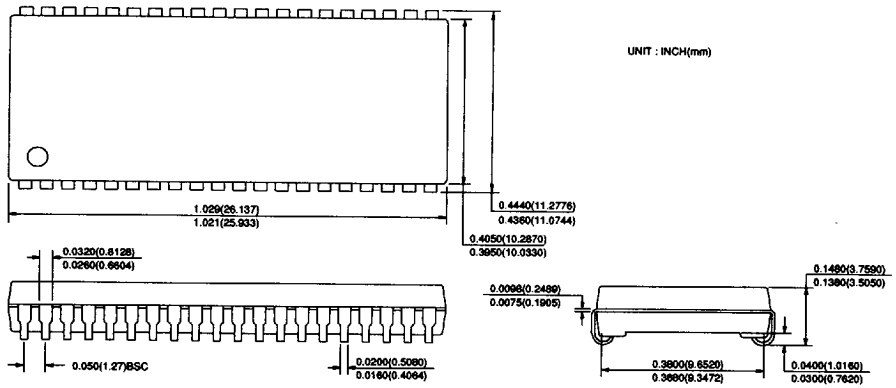
NOTE : A0-9, WE and OE = "H" or "L"

**CAS-BEFORE-RAS REFRESH COUNTER TEST CYCLE**

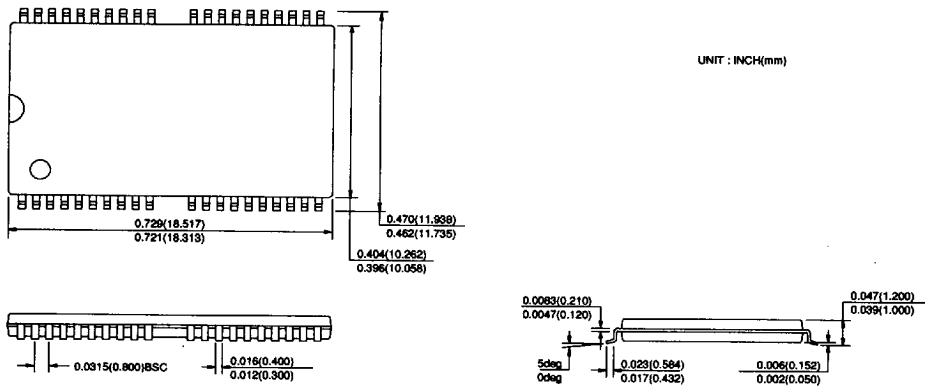


**PACKAGE INFORMATION**

**400 mil 40 pin Small Outline J-form Package (JC)**



**400 mil 40/44 pin Thin Small Outline Package (TC) (RC)**



**ORDERING INFORMATION**

PART NUMBER	SPEED	POWER	PACKAGE
HY514170BJC	60/70/80		SOJ
HY514170BLJC	60/70/80	L-part	SOJ
HY514170BSLJC	60/70/80	SL-part	SOJ
HY514170BTC	60/70/80		TSOP-II
HY514170BLTC	60/70/80	L-part	TSOP-II
HY514170BSLTC	60/70/80	SL-part	TSOP-II
HY514170BRC	60/70/80		TSOP-II(R)
HY514170BLRC	60/70/80	L-part	TSOP-II(R)
HY514170BSLRC	60/70/80	SL-part	TSOP-II(R)